

STS Etch Rates Are All in Angstroms / min

Films	PECVD Nitride-340	PECVD Oxide-340	Thermal Oxide	Low Stresses Nitride	Regular Nitride	Resist 1813	Resist 1818	Resist NR-7 1500P	Resist AZ 1505 *	Resist AZ 1512 *	Bare Silicon Wafer
Recipes											
nit1.set	2173	370	326	801	737	771	736	882	737	735	1536
nit2.set	1616	147	148	437	94	366	343	388	365	340	730
nit3.set	818	45	43	140	94	142	170	193	177	175	514
fastpoly.set	2350	279	216	640	880	376	600	852	728	706	12853
pjsnitd1.set	2090	586	572	213	1243	1210	1200	1269	1245	1215	3756
slowpoly.set	731	70	38	22	250	140		239	197	192	5050
tyb-test.set	149	336	317	99	230	60		134	48	43	367
pjsoxide.set	161	331	303	60 *	220	124	93	135	84	77	92
O2clean.set						1500	1450	1532	1456	1367	-4

All etch rates were taken with a single wafer after a 15 min clean and a 2 min coating etch.

Remember these values are only to be used as a guide, you must verify results yourself.

*These are newer or updated values within 2018